

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Jin-Wan JEON	09/06/2007
Jun-Bo YOON	09/06/2007
Koeng Su LIM	09/14/2007
RECEIVING PARTY DATA	
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State/Country:	KOREA, DEMOCRATIC PEOPLE'S REPUBLIC OF
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11911897
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CH \$40.00 11911897

DOCKET NO.

PATENT

Joint Inventors

(Pending Application:
Serial No. Known)

ASSIGNMENT

WHEREAS, we JEON, Jin-Wan, YOON, Jun-Bo and LIM, Koeng Su, hereinafter referred to as the assignors, residing respectively at Division of Electrical Engineering, Department of Electrical Engineering & Computer Science of KAIST, 373-1 Guseong-dong, Yuseong-gu, Daejeon 305-701, Republic of Korea; Division of Electrical Engineering, Department of Electrical Engineering & Computer Science of KAIST, 373-1 Guseong-dong, Yuseong-gu, Daejeon 305-701, Republic of Korea; and Division of Electrical Engineering, Department of Electrical Engineering & Computer Science of KAIST, 373-1 Guseong-dong, Yuseong-gu, Daejeon 305-701, Republic of Korea are the joint inventors of certain inventions or improvements for which we have made application for Letters Patent to the United States, identified as Case No. 11/911,897, Filing Date 10/18/07, entitled POLYMER OR RESIST PATTERN, AND METAL FILM PATTERN, METAL PATTERN AND PLASTIC MOLD USING THE SAME, AND FABRICATION METHODS THEREOF; and

WHEREAS, Korea Advanced Institute of Science and Technology hereinafter referred to as the assignee, of 373-1, Guseong-dong, Yuseong-gu, Daejeon, Republic of Korea, a university of Korea, is desirous of acquiring the entire right, title and interest in and to the said inventions or improvements and in and to the said application, and in, to and under any and all Letters Patent which may be granted on or as a result thereof in any and all countries:

NOW, THEREFORE, for and in consideration of the sum of One Dollar (\$1.00) to each of us in hand paid by said assignee, and other good and valuable consideration, the receipt of which is hereby acknowledged, we, the said assignors, have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over to said assignee, the entire right, title and interest in and to said inventions or improvements and said application and any and all continuations, divisions and renewals of and substitutes for said application, and in, to and under any and all Letters Patent which may be granted on or as a result thereof in the United States and any and all other countries, and any reissue or reissues or extension or extensions of said Letters Patent, and assign to and authorize said assignee, to file in our names applications for Letters Patent in all countries, the same to be held and enjoyed by said assignee, its successors, assigns, nominees or legal representatives, to the full end of the term or terms for which said Letters Patent respectively may be granted, reissued or extended, as fully and entirely as the same would have been held and enjoyed by us had this assignment, sale and transfer not been made.

AND we hereby covenant that we have full right to convey the entire interest herein assigned, and that we have not executed and will not execute any agreement in conflict herewith, and we further covenant and agree that we will each time request is made and without undue delay, execute and deliver all such papers as may be necessary or desirable to perfect the title to said inventions or improvements, said application and said Letters Patent to said assignee, its successors, assigns, nominees, or legal representatives, and each of us agrees to communicate to said assignee or to its nominee all known facts respecting said inventions or improvements, said

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to execute all disclaimers and divisional, continuing, reissue and foreign applications, to make all rightful oaths, and generally to do everything possible to aid said assignee, its successors, assigns, nominees and legal representatives to obtain and enforce for its or their own benefit proper patent protection for said inventions or improvements in any and all countries.

AND we hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any country or countries foreign to the United States whose duty it is to issue patents on applications as aforesaid, to issue to said assignee, as assignee of the entire right, title and interest, any and all Letters Patent for said inventions or improvements, including any and all Letters Patent of the United States which may be issued and granted on or as a result of the application aforesaid, in accordance with the terms of this assignment.

AND this Assignment may be executed in multiple counterparts, each of which shall be deemed to be an original of this Assignment. Additionally, we hereby authorize our attorneys to collect the signature pages of each executed counterpart and to attach those signature pages to a single copy of this instrument, which single copy and attached signature pages together shall constitute an original of this Assignment.

We further authorize and direct our attorneys to insert below* the serial number and filing date of said application now identified as Case No. @@ as soon as the same shall have been made known to them by the United States Patent Office.

IN WITNESS WHEREOF, we have hereunto set our hands and seals.

JEON, Jin-Wan
Date Sept. 6, 2007

Jin-Wan Jeon (L.S.)

YOON, Jun-Bo
Date Sept. 6, 2007

[Signature] (L.S.)

LIM, Koeng Su, ~~Sept. 14, 2007~~
Date Sept. 14, 2007

Lim Koeng-su (L.S.)

* The above assignment covers application Serial No. 11/911,897 filed on 10-18, year of 2007.

The above insertion made by me this 9th day of June, year of 2008.

[Signature]
Name: Brian L. Belles
Registration No 51,322